



Title of Change:	KAF-16801 datasheet update: Correction of errors induced by incorrect copy/paste actions.	
Effective date:	2 February 2018	
Contact information:	Contact your local ON Semiconductor Sales Office or < John.Frenett@onsemi.com >	
Type of notification:	This Product Bulletin is for notification purposes only. ON Semiconductor will proceed with implementation of this change upon publication of this Product Bulletin.	
Change category:	<input type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input checked="" type="checkbox"/> Other <u>Documentation</u>	
Change Sub-Category(s): <input type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Material Change <input checked="" type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____		
Sites Affected:	ON Semiconductor Sites: ON Rochester, New York	External Foundry/Subcon Sites: None
Description and Purpose: 1) Table 9 (CLOCK LEVELS) has been updated, as follows: a. Nominal value for Horizontal CCD Clock – Phase 1 was 2.0 V; now reads 8.0 V b. Nominal value for Horizontal CCD Clock – Phase 2 was 2.0 V; now reads 8.0 V The change will not impact form, fit, or function of KAF-16801 image sensors.		
List of Affected Standard Parts: KAF-16801-AAA-DP-AE KAF-16801-AAA-DP-B1 KAF-16801-AAA-DP-B2		